IPC-A-600

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May 2016

Acceptability of Printed Boards

Developed by

BUILD ELECTRONICS BETTER

participants from 14 countries contributed to this standard

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IPC-A-600K

Acceptability of Printed Boards

If a conflict occurs between the English and translated versions of this document, the English version will take precedence.

Developed by the IPC-A-600 Task Group (7-31a) of the Product Assurance Committee (7-30) of IPC

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